

ADHESIVE AGENT, ADHESIVE FILM, AND SEMICONDUCTOR DEVICE AND
METHOD FOR MANUFACTURING SAME
TECHNICAL FIELD

Abstract

The present invention relates to an adhesive agent which can be used in the mounting of a semiconductor chip on a circuit board or the like. The present invention addresses the problem of providing an adhesive agent having both excellent storage stability and excellent connection reliability. A means for solving the problem is an adhesive agent comprising (a) a polyamide, (b) an epoxy compound and (c) an acid-modified rosin.

[No suitable figure]